TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

2SK2843

Chopper Regulator, DC-DC Converter and Motor Drive Applications

• Low drain-source ON resistance : RDS (ON) = 0.54Ω (typ.)

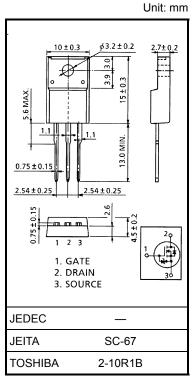
• High forward transfer admittance $: |Y_{fs}| = 9.0 \text{ S (typ.)}$

• Low leakage current $: I_{DSS} = 100 \mu A \text{ (max) (V}_{DS} = 600 \text{ V)}$

• Enhancement mode : $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

Characteri	stics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	600	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V _{DGR}	600	V	
Gate-source voltage	Gate-source voltage		±30	V	
Drain current	DC (Note 1)	I _D	10	Α	
Diam current	Pulse (Note 1)	I _{DP}	40	Α	
Drain power dissipation (Tc = 25°C)		P _D	45	W	
Single pulse avalanche energy (Note 2)		EAS	363	mJ	
Avalanche current		I _{AR}	10	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	5.0	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	



Weight: 1.9 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	2.78	°C / W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 6.36 mH, R_{G} = 25 Ω , I_{AR} = 10 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.

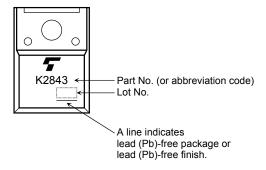
Electrical Characteristics (Ta = 25°C)

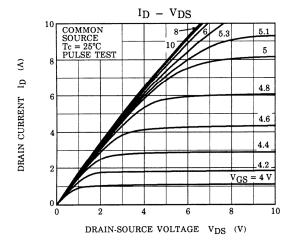
Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	_	_	±10	μΑ
Gate-source bro	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 600 V, V _{GS} = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	600	_	_	V
Gate threshold v	oltage/	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 5 A	_	0.54	0.75	Ω
Forward transfe	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 5 A	3.0	9.0	_	S
Input capacitano	e	C _{iss}		_	2040	_	
Reverse transfer capacitance Output capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	230	_	pF
		C _{OSS}	_	590	_		
Switching time	Rise time	t _r	V_{GS}^{10V} V_{OUT} V_{DD} V_{DD} V_{DD}	_	22	_	ns
	Turn-on time	t _{on}		_	58	_	
	Fall time	t _f		_	36	_	
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\mathbf{W}} = 10 \mu \text{s}$	l	190	l	
Total gate charge (gate-source plus gate-drain)		Qg			45	ı	
Gate-source charge		Q _{gs}	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 10 A		25	_	nC
Gate-drain ("miller") Charge		Q _{gd}		_	20		

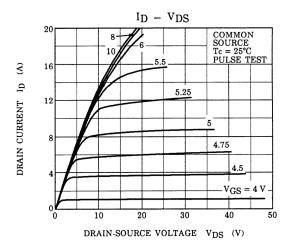
Source-Drain Ratings and Characteristics (Ta = 25°C)

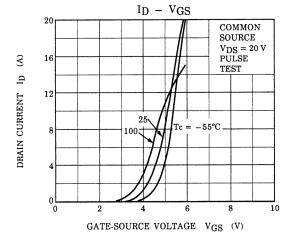
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	10	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	40	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 10 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 10 A, V _{GS} = 0 V		1300		ns
Reverse recovery charge	Q _{rr}	dl _{DR} / dt = 100 Å / μs	_	16	_	μC

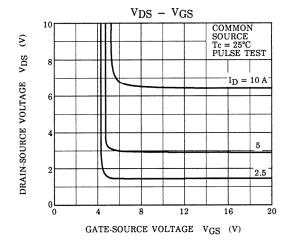
Marking

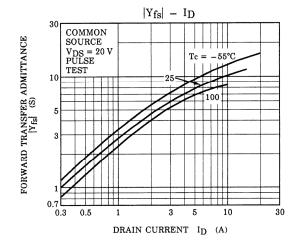


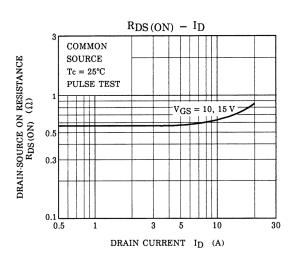




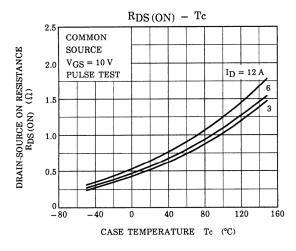


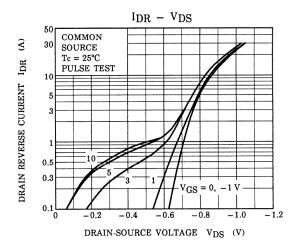


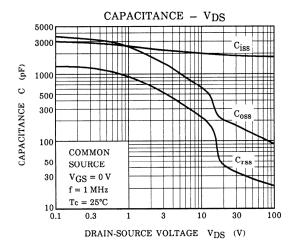


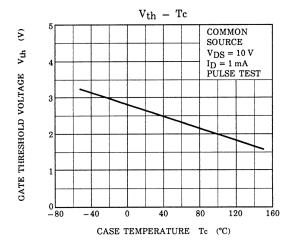


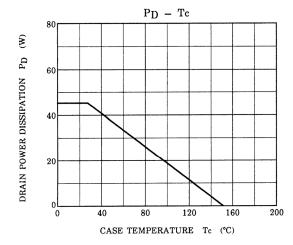
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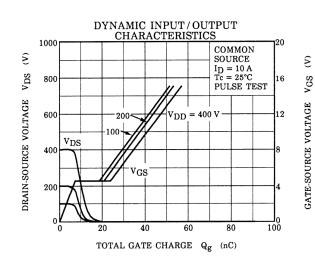






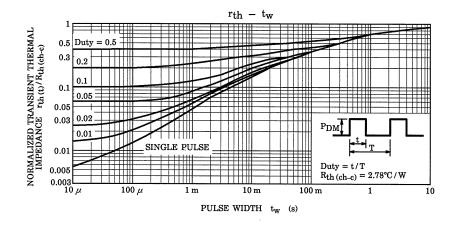


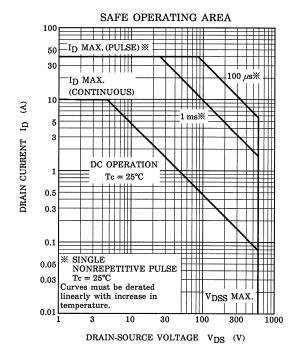


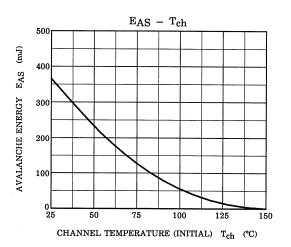


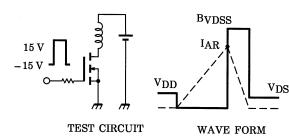
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$$R_G$$
 = 25 Ω V_{DD} = 90 V, L = 6.36 mH $EAS = \frac{1}{2}$

$$EAS = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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